TOKUYAMA EE-BOND

Light-Cured Dental Adhesive



The Enamel-Etching Bonding System

- Excellent bonding to enamel and dentin
- Long-term marginal integrity
- Reduced post-operative sensitivity
- High viscous etching gel



TOKUYAMA ETCHING GEL HV

Extra fine dispensing tip (27G: φ0.4mm)

TOKUYAMA EE-BOND is a dental adhesive system formulated for the enamel-etching technique. This system requires just etching the uncut enamel margins surrounding the preparation. With a diameter of only 0.4mm (27G), the dispensing tip for TOKUYAMA ETCHING GEL HV enables a tracing-like application directly to the margins of the preparation.



TOKUYAMA ETCHING GEL HV

High viscous gel

Drawing the etchant line on a tooth is different than drawing on a canvas. The tooth is not smooth, but consists of grooves, uneven areas and at times sharp edges. With a creamy-like texture, TOKUYAMA ETCHING GEL HV dispenses smoothly onto the tooth and will not run; reliably etching only the surface where the gel is applied.



TOKUYAMA ETCHING GEL HV

Initial



Enamel etching



Finished restoration (Estelite Σ Quick)

Photos: Courtesy of Dr. Kazunori Otani

Outstanding adhesion performance

Utilizing Tokuyama's 3D self-reinforcing (SR) monomer, TOKUYAMA EE-BOND chemically bonds to both enamel and dentin forming a durable 3D matrix bonding layer. This thin but durable bonding layer offers long-term marginal integrity of the esthetic restoration as well as exceptional dentinal sealing.



Micro Tensile Bond Strength (MPa)*

TOKUYAMA EE-BOND



Excellent cavity adaptation

Exceptional dentinal sealing

Easy to visualize, easy to rinse

The dark red color of TOKUYAMA ETCHING GEL HV enables you to clearly visualize the application of the gel to the tooth. The red gel is easily rinsed with water in just 5+ seconds.



After water rinsing

Dependable marginal integrity, reduced post-operative sensitivity

TOKUYAMA EE-BOND penetrates the tooth surface while mildly demineralizing the hydroxyapatite; this advanced technology simultaneously ensures a mechanical retention and chemical bond. No acid etch is required to cut enamel and dentin. Utilizing a limited acid etch technique applied to the uncut enamel margin, TOKUYAMA EE-BOND significantly reduces post-operative sensitivity.



Indications: Bonding of light- or dual-cured composite to: 1. cut/uncut enamel 2. cut/uncut dentin **3. fractured porcelain/**

composite repair



No marginal leakage observed (Result of dye immersion test*)

Clinical Procedure

1 Enamel Etching



Apply TOKUYAMA ETCHING GEL HV only to uncut enamel surrounding margin of prepared cavity and wait for 5 sec



Apply EE-BOND and wait for 10 sec

2 Rinse

Rinse the etched surface thoroughly (at least 5 sec) with water



Apply weak air for 5 sec \rightarrow mild air for 5+sec

3 Drying



Apply mild air to dry



Light cure for 10+sec

Product Packages Available





tokuyama EE-BOND	
Intro-Kit	EE-BOND Bottle/5mL x 1 Disposable Applicator (Superfine) x 25 Dispensing Well x 1 TOKUYAMA ETCHING GEL HV Syringe/2.5mL x 1 TOKUYAMA ETCHING GEL HV Syringe Tip x 10
Refill	EE-BOND Bottle/5mL x 1

TOKUYAMA ETCHING GEL HV



Tip RefillSyringe Tip x 50

Availability of some products is limited in certain areas. Contact your local dealer for more information.

Specifications are subject to change without obligation on the part of the Manufacturer.

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